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With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

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# CHO-BOND® 1035

## ONE COMPONENT ELECTRICALLY CONDUCTIVE SILICONE SEALANT



### Customer Value Proposition:

CHO-BOND® 1035 is a silver-plated glass filled, one-component conductive silicone designed for use as a fillet, gap filler and seam sealant for electrical enclosures where EMI shielding or electrical grounding is required. Minimum recommended bond line for CHO-BOND 1035 is 0.007 inches (0.18 mm). The lightweight silver glass filler of CHO-BOND 1035 provides a low cost EMI shielding solution for a variety of commercial and military applications including applications where weight savings are critical. CHO-BOND 1035's moisture cure silicone polymer system allows it to cure to the touch in 24 hours and provides a flexible, conductive and environmental seal over a wide range of application temperatures.

For best adhesion results, CHO-BOND 1035 should be used in conjunction with CHO-SHIELD 1086 primer. Typical applications include man portable electronics, radar and communication systems, EMI vents, military ground vehicles, and shelters. However, due to its spherical shaped silver plated glass filler, CHO-BOND 1035 is not recommended for equipment or applications where the material will experience vibration.

### Contact Information:

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### Features and Benefits:

- One component
- Silver plated glass filler
- Moisture cure silicone
- Light weight
- Non corrosive cure mechanism
- Thin paste
- Easy to use, no weighing or mixing required.
- Good Conductivity 0.050 ohm -cm  
Low cost (\$/cc).
- 30 minute working life, rapid skin formation, 24 hr handling time, requires no pressure during curing, wide range of application temperatures. 1 week for full cure.
- More coverage per gram of material, minimal weight added to assembly or vehicle.
- No corrosive by-products generated during curing to damage substrate.
- Very easy to dispense, apply and spread.



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## CHO-BOND 1035 - Product Information

Table 1 Typical Properties

CHO-BOND 1035		
Typical Properties	Typical Values	Test Method
Polymer	Silicone	N/A
Filler	Silver-Plated Glass	N/A
Mix Ratio, A : B (by weight)	1-part	N/A
Color	Beige	N/A (Q)
Consistency	Thin Paste	N/A (Q)
Maximum DC Volume Resistivity	0.050 ohm-cm	CHO-95-40-5555* (Q/C)
Minimum Lap Shear Strength**	100 psi (689 kPa)	CHO-95-40-5300* (Q/C)
Minimum Peel Strength**	3.0 lb./inch (525 N/m)	CHO-95-40-5302* (Q/C)
Specific Gravity	1.9	ASTM D792 (Q/C)
Hardness	81 Shore A	ASTM-D2240 (Q/C)
Continuous Use Temperature	- 55 °C to 200 °C (-67 °F to 392 °F)	N/A (Q)
Elevated Temperature Cure Cycle	None	N/A
Room Temperature Cure	1 week***	N/A (Q)
Working Life	0.5 hour	N/A (Q)
Shelf Life, unopened	6 months @ 25°C (77°F)	N/A (Q)
Minimum thickness recommended	0.007 in (0.18 mm)	N/A
Maximum thickness recommended	0.125 in (3.18 mm)	N/A
Volatile Organic Content (VOC)	160 g/l	Calculated
Theoretical Coverage Area at 0.010" Thick per Pound (454 grams)	1450 in <sup>2</sup> (9355 cm <sup>2</sup> )	N/A
Theoretical Coverage - Length of an 1/8" Diameter Bead per Pound (454 grams)	95 feet (29.0 m)	N/A

Note: N/A – Not Applicable, (Q/C) - Qualification and Conformance Test, (Q) - Qualification Test

\* This test Method is available from Parker Chomerics.

\*\* Minimum values listed are based on using the CHO-SHIELD 1086 primer that typically comes bundled with the CHO-BOND.

\*\*\* Cure is sufficient for handling in 24 hours. Full specification properties are developed after 1 week (168 hours) at room temperature.

Table 2 Ordering Information

Product	Weight (grams)	Packaging	Part Number	Primer Included
CHO-BOND 1035	71	1.5 fluid ounce aluminum foil tube	51-00-1035-0000	1086
	71	1.5 fluid ounce aluminum foil tube	51-00-1035-1000	No
	284	6 fluid ounce SEMCO cartridge	51-01-1035-0000	1086

Note: Supplied in a plastic 6 fluid ounce cartridge suitable for standard air-operated caulking guns. To achieve maximum shelf life/pot life, caulking gun should be activated with dry bottled nitrogen.

Table 3 Primer Ordering Information

Product	Weight (grams)	Packaging	Part Number
CHO-BOND 1086	10	3 dram glass vial	50-10-1086-0000
	95	4 fluid ounce glass bottle	50-04-1086-0000
	375	1 pint can	50-01-1086-0000

Please refer to Parker Chomerics Surface Preparation and CHO-BOND Application documents for information regarding the proper surface preparation, primer application (if required), and use of these compounds.

[www.chomerics.com](http://www.chomerics.com)

[www.parker.com/chomerics](http://www.parker.com/chomerics)

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